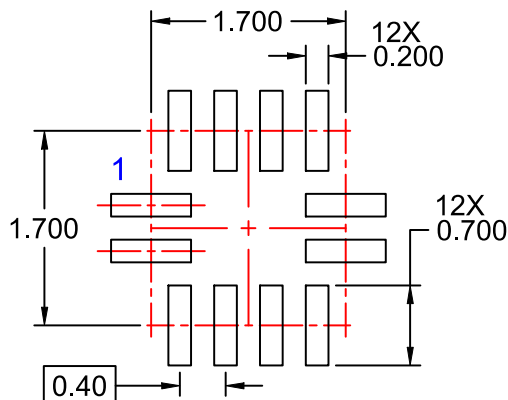
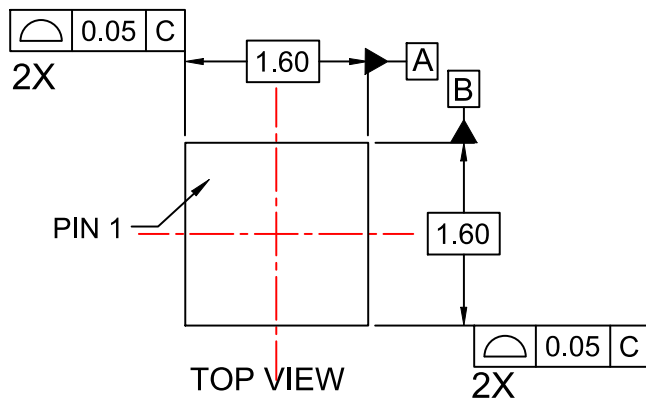


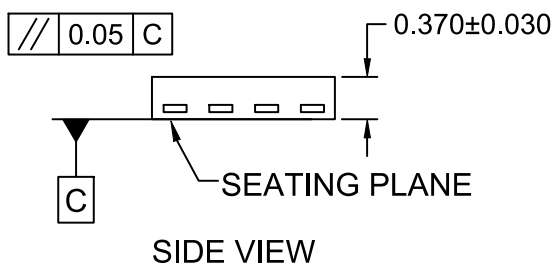


**X2QFN12 1.6x1.6, 0.4P**  
CASE 722AD  
ISSUE O

DATE 31 OCT 2016



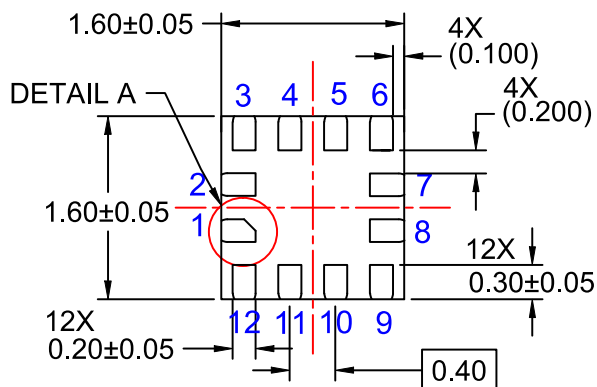
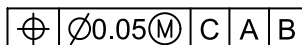
LAND PATTERN RECOMMENDATION



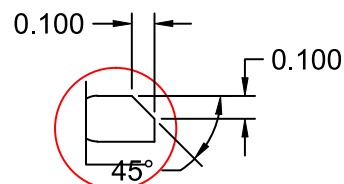
SIDE VIEW

**NOTES:**

- A. NO JEDEC REGISTRATION APPLIES.
- B. DIMENSIONS ARE IN MILLIMETERS.
- C. DIMENSIONS AND TOLERANCE PER ASME Y14.5M, 2009.
- D. PACKAGE NOMINAL HEIGHT IS 370 MICRONS.



BOTTOM VIEW



DETAIL A 2X

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<b>DESCRIPTION:</b>	<b>X2QFN12 1.6x1.6, 0.4P</b>	<b>PAGE 1 OF 1</b>

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